



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Hideyuki KURITA et al.

Application No.: 09/688,181

Filed: October 16, 2000

Group Art Unit: 2825

Examiner: G. Lee

Docket No.: 107594

For: MULTILAYER FLEXIBLE WIRING BOARDS AND PROCESSES FOR
MANUFACTURING MULTILAYER FLEXIBLE WIRING BOARDS

AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed March 14, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 1, 5, 7-9, 14 and 15 without prejudice to or disclaimer of the subject matter contained therein.

Please replace claims 2-4, 6 and 10 as follows:

2. (Amended) A process for manufacturing a multiplayer flexible wiring board by bonding metal wirings of at least two flexible wiring board pieces having a base film including a resin film and a metal wiring provided on said base film, said process comprising:
contacting the tip of an ultrasonic resonator with an exposed opposite side of a portion to be bonded of said metal wirings of at least one flexible wiring board piece of two flexible wiring board pieces to be bonded; and

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